KLA+

Product Fact Sheet

C205

Broadband plasma optical patterned wafer inspection system discovers defects that affect the yield and reliability of semiconductor chips

BENEFITS:

The C205 provides high sensitivity discovery and binning of critical defects, helping automotive chipmakers:

- Accelerate R&D and ramp cycle time through characterization and optimization of new processes, design nodes and devices
- Implement defect reduction strategies to meet chip quality requirements
- Reduce die overkill by providing accurate, actionable data on reliability-related defects
- Detect and characterize sub-design rule defects that can become latent defect escapes

TECHNOLOGIES:

- Tunable DUV, UV, visible broadband illumination source
- Selectable optical apertures
- Low-noise sensor
- NanoPoint™ technology
- Advanced defect detection algorithms
- Automated defect binning

APPLICATIONS:

- Systematic defect discovery for R&D and ramp
- Process window qualification
- Process change verification for continuous improvement
- Inline monitoring of critical layers requiring high sensitivity

MARKETS:

Chip manufacturing

larger design node devices for automotive, IoT, 5G, consumer electronics, industrial (military, aerospace, medical)

PLATFORM:

- Customizable configurations
- Extendible
- Upgradeable

WAFER SIZES:

- 300mm
- 200mm

MORE INFORMATION: www.kla.com/products/chip-manufacturing/defect-inspection-review#product-c205

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